

# GLOBAL SEMICONDUCTOR FORUM 2007

Forging relationships with the world's semiconductor manufacturers



Global Semiconductor Forum  
1-4 March 2007 Hong Kong

## Past and present delegates include

### Company

1<sup>st</sup> Silicon  
Agilent  
AMD Saxony  
Agere System  
Atmel  
ATI Technologies Inc  
Austriamicrosystems AG  
Broadcom Corporation  
Chartered Semiconductor Manufacturing  
Cypress Semiconductor Corp  
DongbuAnam Semiconductor  
Elpida Memory  
Fairchild Semiconductor  
Fairchild Semiconductor  
Fujitsu Ltd  
HH NEC Electronics Co. Ltd  
Hynix Semiconductor Inc.  
IBM  
Infineon Technologies  
Inotera Memories Inc  
Intel Corporation  
NEC Electronics America  
Nanya Technology Corporation  
Nanya Technology Corp  
National Semiconductor  
Philips Semiconductor (Assembly & Test Organization)  
Promos Technology  
Powerchip Semiconductor Corporation  
Renesas Technology  
Samsung Electronics  
Shanghai Belling Ltd  
SMIC  
Spansion LLC  
Sony Corporation  
St Microelectronics  
Taiwan Semiconductor Manufacturing Company Ltd  
Texas Instruments Incorporated  
Toshiba Corporation  
Toshiba Corporation  
TSMC  
VIA Technologies  
Winbond Electronics Corp.

### Position

Manufacturing Project director  
VP Global Sourcing  
VP  
EVP Operations  
VP Process Development  
VP Asian Operations  
VP Purchasing  
VP Manufacturing  
VP Fab Operations (Fab2,3,5)  
VP  
SEVP Manufacturing  
CTO  
EX. VP Global Operations  
SVP & MD  
GM Device Development Division LSI Group  
VP Operations  
Chief Operating Officer  
Director 300mm Semiconductor Operation  
SVP Production Memory product group  
SVP Production  
Director Fab Capital Development group  
Vice president  
Vice President  
VP Manufacturing & Development  
SVP World Wide Operations  
VP Operations  
Dir. 300mm Programme  
VP Operations  
Executive General Manager Production &  
EVP & GM Fab Centre  
Fab Director  
COO  
Corp. VP  
GM Assistant to NC President  
Group VP Central Red R2 Technology Center  
Director Manufacturing Technology Centre  
TI Fellow, Platform Director  
Corporate VP  
Sr. Manager, Broadband System LSI Division  
Sr Director Assembly & Test Technology  
VP Manufacturing & Product Engineering  
Director 300mm Module and Integration Division